#### SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES SDLS124 – DECEMBER 1972 – REVISED MARCH 1988

SN5486, SN54LS86A, SN54S86 . . . J OR W PACKAGE

SN7486 . . . N PACKAGE SN74LS86A, SN74S86 . . . D OR N PACKAGE

(TOP VIEW)

140 VCC

13 4B

12 4A

110 4Y

10 3B

9 3A 8 3Y

1A 🗗

1Y D3

2A 🛛 4

2B 🛛 5

2Y 16

**Π**7

1B [ 2

GND

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

	TYPICAL AVERAGE	TYPICAL
TYPE	PROPAGATION	TOTAL POWER
	DELAY TIME	DISSIPATION
'86	14 ns	150 mW
'LS86A	10 ns	30.5 mW
'S86	7 ns	250 mW

#### description

These devices contain four independent 2-input Exclusive-OR gates. They perform the Boolean functions  $Y = A \oplus B = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input will be reproduced in true form at the output. If one of the inputs is high, the signal on the other input will be reproduced inverted at the output.

The SN5486, 54LS86A, and the SN54S86 are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7486, SN74LS86A, and the SN74S86 are characterized for operation from 0 °C to 70 °C.

#### exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



**EXCLUSIVE-OR** 

These are five equivalent Exclusive-OR symbols valid for an '86 or 'LS86A gate in positive logic; negation may be shown at any two ports.

LOGIC IDENTITY ELEMENT



The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

EVEN-PARITY



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

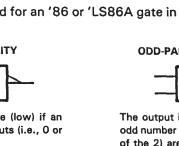
**ODD-PARITY ELEMENT** 

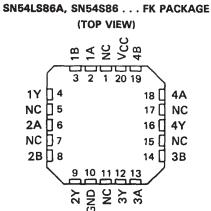


The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.





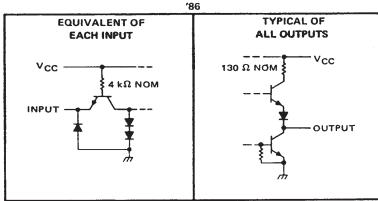
NC - No internal connection

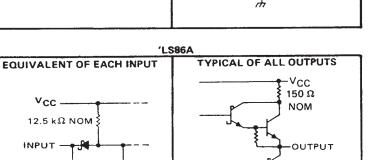
STRUMENTS

#### SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES SDLS124 – DECEMBER 1972 – REVISED MARCH 1988

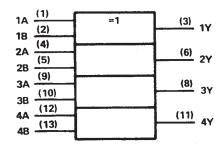
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### schematics of inputs and outputs





### logic symbol<sup>†</sup>



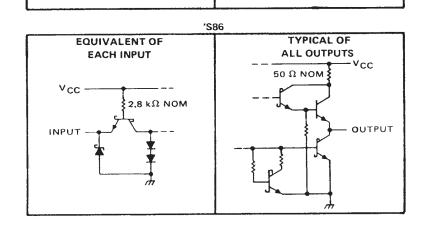
<sup>†</sup>This symbol is in accordance with

ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

#### FUNCTION TABLE

INP	UTS	OUTPUT
A	в	Y
L	L	L
L	н	н
н	L	н
н	н	L

H = high level, L = low level



### SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 **QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES** SDLS124 – DECEMBER 1972 – REVISED MARCH 1988

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)			 									7V
Input voltage												
Operating free-air temperature range: SN5486												
												. 0°C to 70°C
Storage temperature range		•			•	•		•	•	•	•	–65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN5486	5		UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-800			-800	μA
Low-level output current, IOL			16			16	mA
Operating free-air temperature, T <sub>A</sub>	55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS <sup>†</sup>	1	SN5486	3		UNIT		
	PARAMETER	TEST CONDITIONS.	MIN	τγρ‡	MAX	MIN	TYP‡	MAX	UNIT
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			0.8	V
VIK	Input clamp voltage	$V_{CC} = MIN, I_1 = -8 mA$			-1.5			-1.5	V
		$V_{CC} = MIN, V_{IH} = 2V,$	2.4	3.4		2.4	3.4		V
Vон	High-level output voltage	V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -800 µA	2.4	3.4		2.4	5.4		
		V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V		0.2	0.4		0.2	0.4	v
VOL	Low-level output voltage	V <sub>1L</sub> = 0.8 V, 10L = 16 mA		0,2	0.4		0.2	0.4	
4	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
1 <sub>IH</sub>	High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.4 V			40			40	μA
11L	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V	1		-1.6			-1.6	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX	20		-55	-18		-55	mA
1CC	Supply current	V <sub>CC</sub> = MAX, See Note 2		30	43	1	30	50	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. <sup>‡</sup>All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ .

SNot more than one output should be shorted at a time.

NOTE 2: ICC is measured with the inputs grounded and the outputs open.

### switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

PARAMETER¶	FROM (INPUT)	TEST COM	NDITIONS	MIN	түр	мах	UNIT
<sup>t</sup> PLH	A or B	Otheringut low	CL = 15 pF,		15	23	ns
tPHL	AUB	Other input low	$R_{L} = 400 \Omega,$		11	17	
трен	A or B	Other input high	See Note 3		18	30	ns
tPHL	A 01 B	Other input high	See Note S		13	22	

 $f_{tPLH}$  = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



## SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

SDLS124 – DECEMBER 1972 – REVISED MARCH 1988

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	
Operating free-air temperature range: SN54LS86A	25°C
SN74LS86A SN74LS86A Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

	S	N54LS	36A	S	UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-400			-400	μA
Low-level output current, IOL			4			8	mA
Operating free-air temperature, TA	-55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			upizionist	SM	154LS8	6A	SM			
	PARAMETER	TEST CO	NDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	
ViH	High-level input voltage			2			2			V
VIL	Low-level input voltage			1		0.7			0.8	V
Vik	Input clamp voltage	V <sub>CC</sub> = MIN,	li = -18 mA	1		-1.5			-1.5	V
VOH	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max	V <sub>IH</sub> = 2 V, , I <sub>OH</sub> = -400 µA	2.5	3.4		2.7	3.4		v
Mai	Low-level output voltage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	1 <sub>0L</sub> = 4 mA		0.25	0.4		0.25	0.4	
VOL		VIL = VILmax	1 <sub>OL</sub> = 8 mA					0.35	0.5	
4	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V	1		0.2	T		0.2	mA
Чн	High-level input current	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V			40			40	μA
4	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V	1		0.8			-0.8	mA
los	Short-circuit output current <sup>§</sup>	V <sub>CC</sub> = MAX		- 20		- 100	- 20		- 100	mA
Icc	Supply current	V <sub>CC</sub> = MAX,	See Note 2	1	6.1	10		6.1	10	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. <sup>‡</sup>All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}$ C.

SNot more than one output should be shorted at a time.

NOTE 2:  $I_{CC}$  is measured with the inputs grounded and the outputs open.

### switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

PARAMETER¶	FROM (INPUT)	TEST CON	TEST CONDITIONS			MAX	UNIT
tPLH	A or B	Orber input low	$C_{1} = 15 \text{ pc}$		12	23	ns
<sup>t</sup> PHL	AUIB	Other input low	$C_{L} = 15  pF,$	[	10	17	
<sup>t</sup> PLH	A or B	Other input high	R <sub>L</sub> = 2 kQ, See Note 3		20	30	ns
<sup>t</sup> PHL	A or B Other inpu	Other input high	See Note 5	[·	13	22	

 $\P_{tp_{LH}}$  = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



## SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 **QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES**

SDLS124 – DECEMBER 1972 – REVISED MARCH 1988

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)													7V
													5.5 V
Operating free-air temperature range: SN54S86		 •		•				 •		•			–55°C to 125°C
SN74S86		 •		•				 •		•	 •	•	. 0°C to 70°C
Storage temperature range	•	 •	•••	•	•••	• •	• •	 •	•	•	 •		–65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN54S8	6				
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-1			-1	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	-55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS!		SN54S8	6		UNIT		
	PARAMETER	TEST CONDITIONS <sup>†</sup>	MIN	<b>ΤΥΡ</b> ‡	MAX	MIN	TYP‡	MAX	
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			0.8	V
VIK	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>1</sub> =18 mA			-1.2			-1.2	V
VOH	High-level output voltage	$V_{CC} = MIN, V_{1H} = 2V,$ $V_{11} = 0.8V, I_{OH} = -1 mA$	2.5	3.4		2.7	3.4		v
VOL	Low-level output voltage	$V_{CC} = MIN, V_{1H} = 2 V$ $V_{1L} = 0.8 V, I_{0L} = 20 mA$	1		0.5			0.5	v
4	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V	<u> </u>		1			1	mA
<u>ч</u> н	High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.7 V			50			50	μA
11	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V	1		-2	1		-2	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX	-40		-100	-40		-100	mA
	Supply current	V <sub>CC</sub> = MAX, See Note 2		50	75		50	75	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

<sup>‡</sup>All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}$ C. §Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: ICC is measured with the inputs grounded and the outputs open.

#### switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

PARAMETER	FROM (INPUT)	TEST CONDITIONS				MAX	UNIT
tPLH	A or B	Other input low	C1 = 15 pF,		7	10.5	ns
tPHL	AOFB	Other input low	R <sub>L</sub> = 280 Ω,		6.5	10	ļ
<sup>t</sup> ΡLΗ	A or B	Other input high	See Note 3		7	10.5	ns
трнг		Other input night	000 11010 0		6.5	10	

**1**<sub>tpLH</sub> = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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10-Feb-2010

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/07501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7486N	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN7486N	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN7486N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN7486N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS86AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS86AN	ACTIVE	PDIP	Ν	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type
	=		-					

# PACKAGE OPTION ADDENDUM

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TEXAS INSTRUMENTS

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(;</sup>
						(RoHS)		
SN74LS86AN3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS86AN3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS86ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS86ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86D	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86D	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86DE4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86DE4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86DG4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86DG4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86N	ACTIVE	PDIP	Ν	14	25	TBD	Call TI	Call TI
SN74S86N	ACTIVE	PDIP	Ν	14	25	TBD	Call TI	Call TI
SN74S86N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74S86N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74S86NE4	ACTIVE	PDIP	Ν	14	25	TBD	Call TI	Call TI
SN74S86NE4	ACTIVE	PDIP	Ν	14	25	TBD	Call TI	Call TI
SN74S86NSR	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSR	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSRE4	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSRE4	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSRG4	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSRG4	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SNJ5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5486W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5486W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	A42 A42	N / A for Pkg Type

**W** INSTRUMENTS

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Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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# PACKAGE MATERIALS INFORMATION

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Texas Instruments

## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS86ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS86ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S86NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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# PACKAGE MATERIALS INFORMATION

10-Feb-2010



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS86ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS86ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74S86NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MLCC006B - OCTOBER 1996

### FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## MECHANICAL DATA

### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

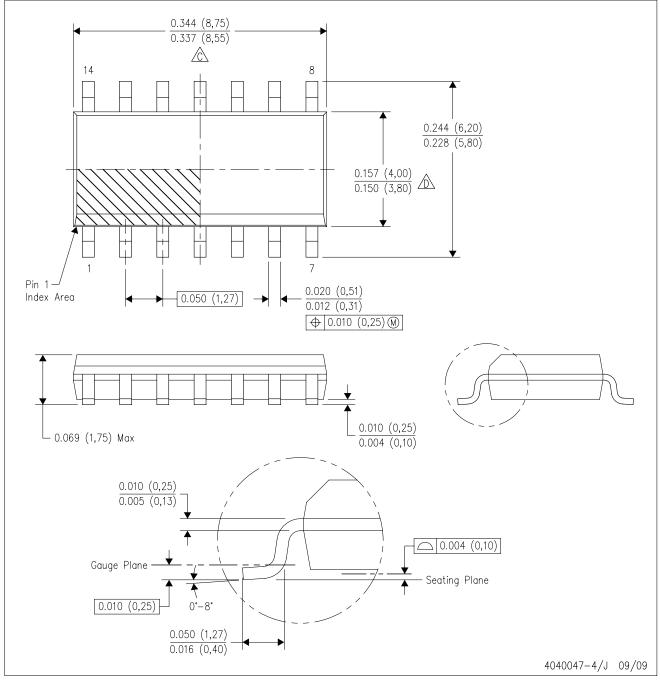
**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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10-Feb-2010

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/07501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7486N	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN7486N	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN7486N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN7486N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS86AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS86AN	ACTIVE	PDIP	Ν	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type
	=		-					

# PACKAGE OPTION ADDENDUM

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TEXAS INSTRUMENTS

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(;</sup>
						(RoHS)		
SN74LS86AN3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS86AN3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS86ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS86ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74LS86ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
SN74S86D	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86D	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86DE4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86DE4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86DG4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86DG4	ACTIVE	SOIC	D	14	50	TBD	Call TI	Call TI
SN74S86N	ACTIVE	PDIP	Ν	14	25	TBD	Call TI	Call TI
SN74S86N	ACTIVE	PDIP	Ν	14	25	TBD	Call TI	Call TI
SN74S86N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74S86N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74S86NE4	ACTIVE	PDIP	Ν	14	25	TBD	Call TI	Call TI
SN74S86NE4	ACTIVE	PDIP	Ν	14	25	TBD	Call TI	Call TI
SN74S86NSR	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSR	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSRE4	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSRE4	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSRG4	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SN74S86NSRG4	ACTIVE	SO	NS	14	2000	TBD	Call TI	Call TI
SNJ5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5486J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ5486W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5486W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	A42 A42	N / A for Pkg Type

**W** INSTRUMENTS

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Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S86W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS86ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS86ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S86NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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# PACKAGE MATERIALS INFORMATION

10-Feb-2010



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS86ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS86ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74S86NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MLCC006B - OCTOBER 1996

### FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## MECHANICAL DATA

### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

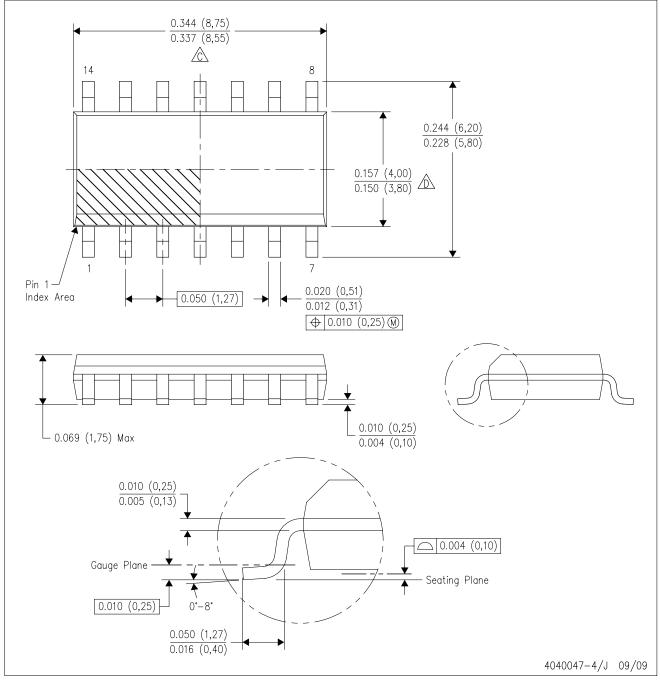
**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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DSP	dsp.ti.com	Computers and Peripherals	www.ti.com/computers
Clocks and Timers	www.ti.com/clocks	Consumer Electronics	www.ti.com/consumer-apps
Interface	interface.ti.com	Energy	www.ti.com/energy
Logic	logic.ti.com	Industrial	www.ti.com/industrial
Power Mgmt	power.ti.com	Medical	www.ti.com/medical
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Space, Avionics & Defense	www.ti.com/space-avionics-defense
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video and Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless-apps

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